## PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Hidekazu Miyairi	07/25/2015
Kazuya HANAOKA	07/28/2015
Suguru Hondo	07/15/2015
Shunpei Yamazaki	07/28/2015

## **RECEIVING PARTY DATA**

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Street Address:	398, HASE, ATSUGI-SHI
City:	KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14462824

## **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	KRISTI A. HOLMLUND
SIGNATURE:	/Kristi A. Holmlund/
DATE SIGNED:	09/03/2015

**Total Attachments: 2** 

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> **PATENT REEL: 036489 FRAME: 0255** 503465881

# ASSIGNMENT

For valuable consideration, We, <u>Hidekazu MIYAIRI of Hadano</u>, <u>Kanagawa, Japan, Kazuya HANAOKA of Pujisawa</u>, <u>Kanagawa, Japan, Suguru HONDO of 1-25-20</u>, <u>Kamiohokahigashi</u>, <u>Konan-ku, Yokohama-shi</u>, <u>Kanagawa-ken, 233-0001</u>, <u>Japan and Shunpei YAMAZAKI of Setagaya</u>, <u>Tokyo</u>, <u>Japan hereby assign to <u>Semiconductor Fnergy Laboratory Co.</u>, <u>Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:</u>

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME, filed August 19, 2014, and assigned U.S. Serial Number 14/462,824, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature	Hiderazu MIYAIRI			
Name:	Hidekazu MIYAIRI			
Date:	07/25/2015			
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Signature	Kazinja Hornaoka Kazinja HANAOKA			
Name:	Kazuya HANAOKA			
Date:	07/28/2015			

PATENT REEL: 036489 FRAME: 0256

Signature	Suzuru Hondo	
Name:	Suguru HONDO	
Date:	15/09/2015	
Signature	Shaw Co	ande
Name:	Shunpei YAMAZAKI	
Date:	09/28/10/5	

PATENT REEL: 036489 FRAME: 0257

**RECORDED: 09/03/2015**